

# EVG620 Face Engraving Machine Refurbishment Equipment

## Technical Specifications

**Equipment Name : EVG620 Lithography Machine**

**Equipment Model : EVG620**

**Equipment purpose and function :** The process of transferring the geometry of a photomask to the surface of a silicon wafer .

### Equipment configuration:

serial number	Configuration	describe
1	Wafer Diameter	150mm
2	Wafer Transfer System	Manual
3	Control System	Control Unit, Display, Touch Screen
4	Process Chamber	Lamp
5	With mask holder	7X7
5	Voltage	230V/3 $\Phi$
6	Compressed	6 bar/87 psi
7	N2/CDA	6 bar/87 psi
8	Vacuum	<850mbar/646Torr
9	Lamphouse	500W

### Equipment performance:

project	Technical indicators
Range of alignment	X, Y: $\pm$ 5 mm
Rotation	Theta /- 3.5°
Resolution	1.5 $\mu$ m (0.8um@vacuum chuck)
Top side alignment	0.5 $\mu$ m (With 20x objective)
Equipment light intensity	The light intensity is around 1.5 mw /cm <sup>2</sup>
Light intensity uniformity	< 5 %